

ABSTRACT

A polishing apparatus includes a polishing object holding mechanism for holding an object to be polished, and a table having a polishing surface. The polishing object
5 held by the polishing object holding mechanism is pressed against the polishing surface of the table and polished by relative movement between the polishing object held by the holding mechanism and the polishing surface of the table. An elastic sheet 11 is stretched over the upper surface of
10 the table, and a polishing pad 16 having a polishing surface on the upper side thereof is replaceably stretched over the elastic sheet 11. Thus, the function performed by an underlayer pad member of a double-layer polishing pad that has heretofore frequently been used in a
15 chemical/mechanical polishing (CMP) apparatus is imparted to the table of the chemical/mechanical polishing (CMP) apparatus, thereby achieving cost reduction of chemical/mechanical polishing (CMP) process and stabilizing process performance such as polishing rate uniformity
20 within a substrate surface to be polished.